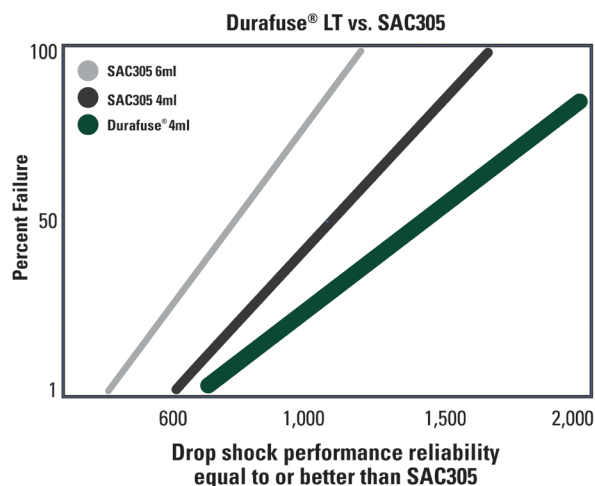
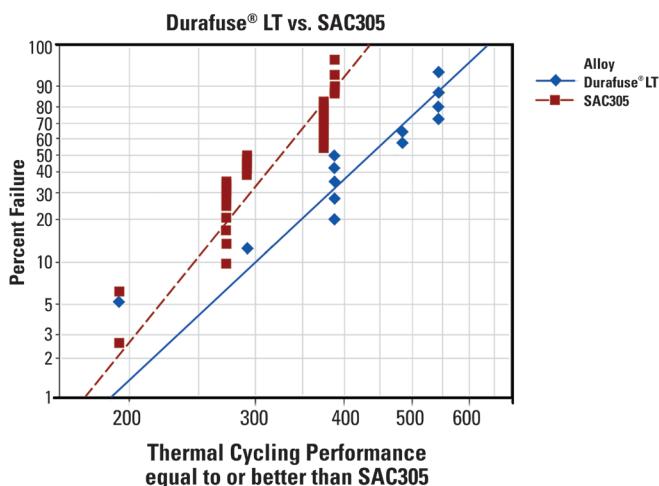


Durafuse[®] LT



Versatile Solution for Your Process Challenges

- ✓ Achieve high reliability while **reducing energy consumption by 10–15%**, compared to SAC305
- ✓ Enable **complex processes and designs**, such as step soldering, large temperature gradients, large BGA warpage, and fine feature printing
- ✓ The only low-temperature solder providing **excellent drop shock reliability**
- ✓ **Superior thermal cycling performance** on next generation component technology



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Durafuse® HR



High-Reliability Alloy Solution

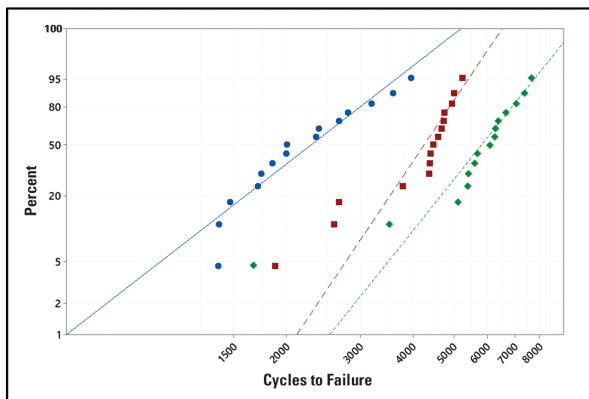
Enhanced thermal cycling reliability with low-voiding performance



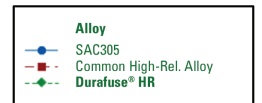
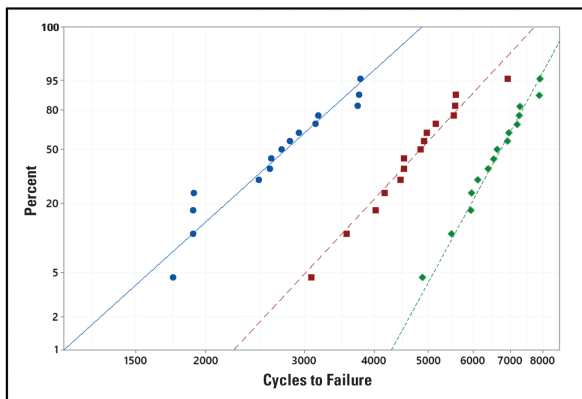
-40/+125°C thermal cycling conditions for 8,000+ cycles

- Reduced solder joint cracking
- Increased shear strength over time
- Longer characteristic lifetime (>3,000 cycles)

-40/125°C – BGA192 – ImSn Surface Finish



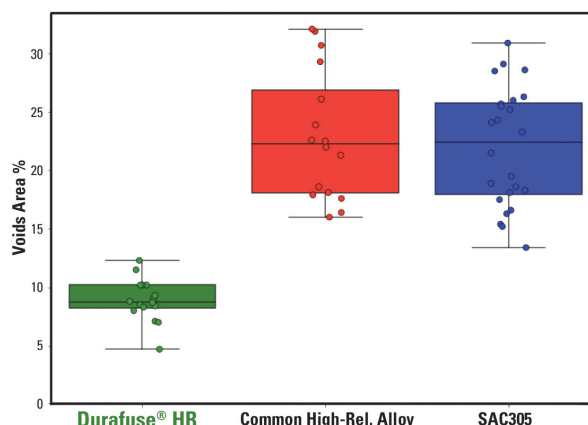
-40/125°C – QFN – ImSn Surface Finish



Superior voiding performance

- BGA, CSP, QFN and other bottom terminated components
- Common Surface Finishes

QFN on ImSn Surface Finish



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